

EMS41GKF-44.000M

[Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Jun 1, 2020)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



ITEM DESCRIPTION

Spread Spectrum MEMS Clock Oscillators LVCMOS (CMOS) 1.8Vdc 4 Pad 2.0mm x 2.5mm Plastic Surface Mount (SMD) 44.000MHz ±100ppm Maximum over -40°C to +85°C Spread Disable (Spread Spectrum On Output Disabled) -2.00% Down

ELECTRICAL SPECIFICATIONS

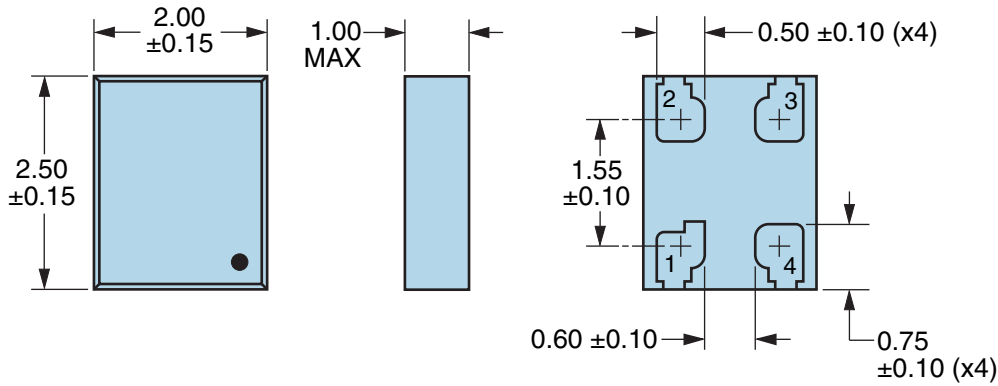
Nominal Frequency	44.000MHz
Frequency Tolerance/Stability	±100ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, 260°C Reflow, Shock, and Vibration)
Aging at 25°C	±1ppm Maximum First Year
Supply Voltage	1.8Vdc ±5%
Maximum Supply Voltage	-0.5Vdc to +1.98Vdc
Input Current	35mA Maximum (Unloaded; Nominal Vdd)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH=-8mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL=+8mA)
Rise/Fall Time	2nSec Maximum (Measured from 20% to 80% of waveform)
Duty Cycle	50 ±5(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Spread Disable (Spread Spectrum On Output Disabled)
Spread Spectrum Input Voltage (Vih and Vil)	70% of Vdd Minimum or No Connection to Enable Spread Spectrum-On Output, 30% of Vdd Maximum to Disable Spread Spectrum-On Output
Spread Spectrum	-2.00% Down Spread
Modulation Frequency	30kHz Minimum, 32kHz Typical, 35kHz Maximum
Period Jitter	90pSec Maximum (Cycle to Cycle; Spread Spectrum-On; Fo=133.333M, Vdd=1.8Vdc)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Pads on Bottom of Package Only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

EMS41GKF-44.000M [Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)

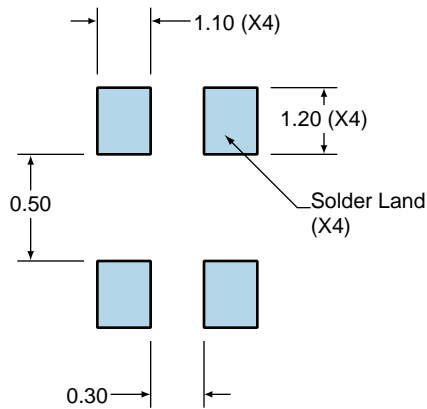


PIN	CONNECTION
1	Spread Disable
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	XXXX or XXXXX XXXX or XXXXX=Ecliptek Manufacturing Identifier

Suggested Solder Pad Layout

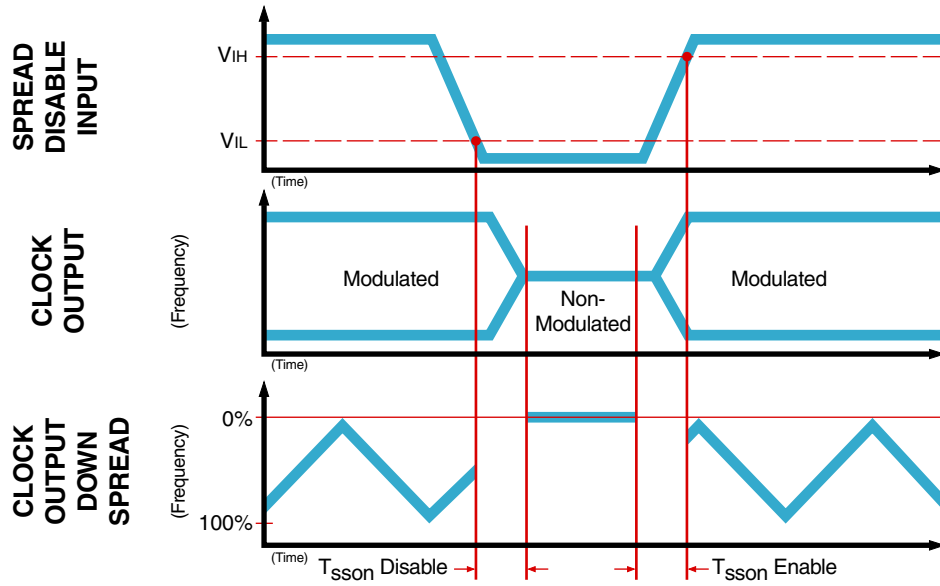
All Dimensions in Millimeters



All Tolerances are ±0.1

EMS41GKF-44.000M [Click part number to visit Part Number Details page](#)

OUTPUT WAVEFORM & TIMING DIAGRAM



EMS41GKF-44.000M

[Click part number to visit Part Number Details page](#)

Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.